

### 1.8mm SOLID STATE LAMP

Part Number: WP2060ID

High Efficiency Red

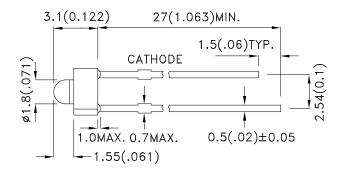
### **Features**

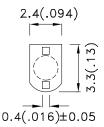
- 1.8mm DIAMETER SMALL SIZE LED LAMP.
- ULTRA BRIGHTNESS IS AVAILABLE.
- RELIABLE AND RUGGED.
- VERSATILE MOUNTING ON P.C. BOARD OR PANEL.
- AVAILABLE IN DIFFUSED LENS.
- RoHS COMPLIANT.

### Description

The High Efficiency Red source color devices are made with Gallium Arsenide Phosphide on Gallium Phosphide Orange Light Emitting Diode.

## **Package Dimensions**





- 1. All dimensions are in millimeters (inches).
- 2. Tolerance is  $\pm 0.25(0.01")$  unless otherwise noted.
- Lead spacing is measured where the leads emerge from the package.
   Specifications are subject to change without notice.





SPEC NO: DSAG0116 APPROVED: WYNEC

**REV NO: V.4 CHECKED: Allen Liu**  **DATE: DEC/08/2007** DRAWN: R.Chen

PAGE: 1 OF 6 ERP: 1101002660

## **Selection Guide**

Part No.	Dice	Lens Type	lv (mcd) [2 @ 10mA		Viewing Angle [1]
		-	Min.	Тур.	201/2
WP2060ID	High Efficiency Red (GaAsP/GaP)	RED DIFFUSED	8	15	70°

- 1. 01/2 is the angle from optical centerline where the luminous intensity is 1/2 the optical centerline value. 2. Luminous intensity/ luminous Flux: +/-15%.

## Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Device	Тур.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	High Efficiency Red	627		nm	IF=20mA
λD [1]	Dominant Wavelength	High Efficiency Red	625		nm	IF=20mA
Δλ1/2	Spectral Line Half-width	High Efficiency Red	45		nm	IF=20mA
С	Capacitance	High Efficiency Red	15		pF	VF=0V;f=1MHz
VF [2]	Forward Voltage	High Efficiency Red	2	2.5	V	IF=20mA
lr	Reverse Current	High Efficiency Red		10	uA	V <sub>R</sub> = 5V

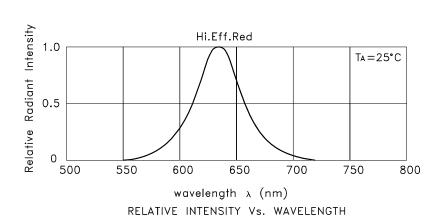
- 1.Wavelength: +/-1nm.
- 2. Forward Voltage: +/-0.1V.

## Absolute Maximum Ratings at TA=25°C

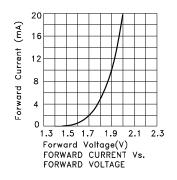
Parameter	High Efficiency Red	Units	
Power dissipation	75	mW	
DC Forward Current	30	mA	
Peak Forward Current [1]	160	mA	
Reverse Voltage	5	V	
Operating/Storage Temperature	-40°C To +85°C	•	
Lead Solder Temperature [2]	260°C For 3 Seconds		
Lead Solder Temperature [3]	260°C For 5 Seconds		

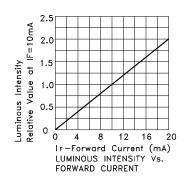
- 1. 1/10 Duty Cycle, 0.1ms Pulse Width.
- 2. 2mm below package base.
- 3. 5mm below package base.

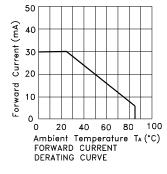
SPEC NO: DSAG0116 **REV NO: V.4 DATE: DEC/08/2007** PAGE: 2 OF 6 APPROVED: WYNEC **CHECKED: Allen Liu** DRAWN: R.Chen ERP: 1101002660

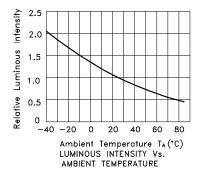


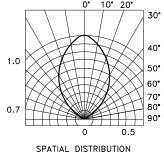
High Efficiency Red WP2060ID





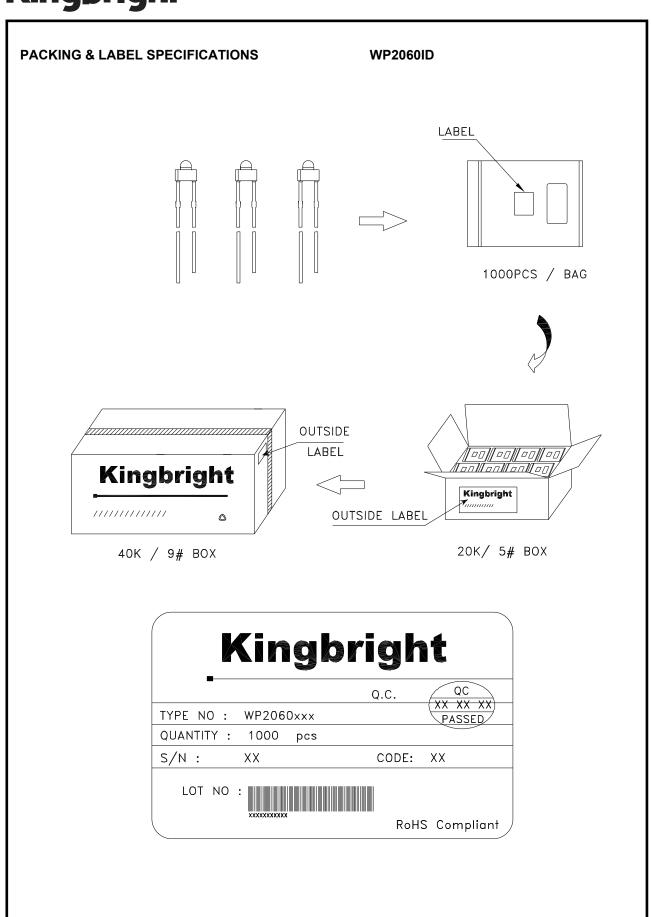






 SPEC NO: DSAG0116
 REV NO: V.4
 DATE: DEC/08/2007
 PAGE: 3 OF 6

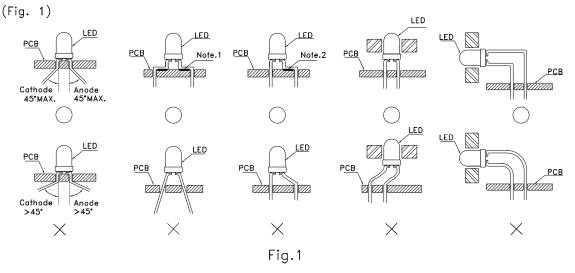
 APPROVED: WYNEC
 CHECKED: Allen Liu
 DRAWN: R.Chen
 ERP: 1101002660



SPEC NO: DSAG0116 APPROVED: WYNEC REV NO: V.4 CHECKED: Allen Liu DATE: DEC/08/2007 DRAWN: R.Chen PAGE: 4 OF 6 ERP: 1101002660

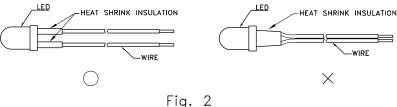
### LED MOUNTING METHOD

1. The lead pitch of the LED must match the pitch of the mounting holes on the PCB during component placement. Lead—forming may be required to insure the lead pitch matches the hole pitch. Refer to the figure below for proper lead forming procedures.



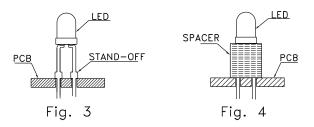
" $\bigcirc$ " Correct mounting method " $\times$ " Incorrect mounting method Note 1-2: Do not route PCB trace in the contact area between the leadframe and the PCB to prevent short-circuits.

2. When soldering wire to the LED, use individual heat—shrink tubing to insulate the exposed leads to prevent accidental contact short—circuit. (Fig. 2)



rig. Z

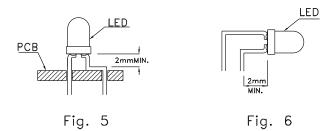
3. Use stand—offs (Fig. 3) or spacers (Fig. 4) to securely position the LED above the PCB.



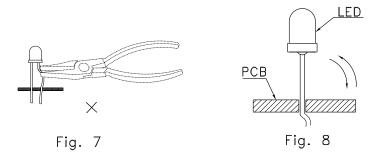
SPEC NO: DSAG0116 APPROVED: WYNEC REV NO: V.4 CHECKED: Allen Liu DATE: DEC/08/2007 DRAWN: R.Chen PAGE: 5 OF 6 ERP: 1101002660

## LEAD FORMING PROCEDURES

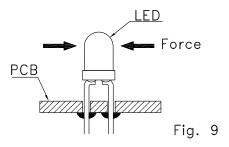
1. Maintain a minimum of 2mm clearance between the base of the LED lens and the first lead bend. (Fig. 5 and 6)



- 2. Lead forming or bending must be performed before soldering, never during or after Soldering.
- 3. Do not stress the LED lens during lead—forming in order to fractures in the lens epoxy and damage the internal structures.
- 4. During lead forming, use tools or jigs to hold the leads securely so that the bending force will not be transmitted to the LED lens and its internal structures. Do not perform lead forming once the component has been mounted onto the PCB. (Fig. 7)
- 5. Do not bend the leads more than twice. (Fig. 8)



6. After soldering or other high—temperature assembly, allow the LED to cool down to 50°C before applying outside force (Fig. 9). In general, avoid placing excess force on the LED to avoid damage. For any questions please consult with Kingbright representative for proper handling procedures.



SPEC NO: DSAG0116 REV NO: V.4

APPROVED: WYNEC CHECKED: Allen Liu

DATE: DEC/08/2007 DRAWN: R.Chen PAGE: 6 OF 6 ERP: 1101002660